

Product / Package Information

Package	LFCSP - Punched
Body Size (mm)	12 X 12 X 0.85 (7.7 EP)
LeadCount	80
Terminal Finish	100 Sn

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
JIG Material Content Compliant	Level A & B Compliant

Materials Declaration**Molding Compound**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	1.34E-01	86.91	869100	34.16	341619
Thermosets	Epoxy & Phenol Resin	Proprietary	1.97E-02	12.78	127800	5.02	50235
Other inorganic materials	Carbon black	1333-86-4	4.78E-04	0.31	3100	0.12	1219
Subtotal			1.54 E-01	100.00	1000000	39.31	393072

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.89 E-01	96.37	963700	48.12	481211
Copper & its alloys	Nickel	7440-02-0	4.89 E-03	2.50	25000	1.25	12483
Copper & its alloys	Silicon	7440-21-3	1.17 E-03	0.60	6000	0.30	2996
Copper & its alloys	Zinc	7440-66-6	9.79 E-04	0.50	5000	0.25	2497
Copper & its alloys	Silver	7440-22-4	5.87 E-05	0.03	300	0.01	150
Subtotal			1.96 E-01	100.00	1000000	49.93	499337

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	6.90 E-04	100.0	1000000	0.18	1760

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	1.00 E-03	100.0	1000000	0.26	2551

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	3.73 E-03	100.0	1000000	0.95	9514

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	3.24 E-02	100.0	1000000	8.27	82670

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	3.19 E-03	73.40	734000	0.81	8144
Thermoset	Epoxy Resin	Proprietary	7.98 E-04	18.35	183500	0.20	2036
Other inorganic materials	Metal oxide	Proprietary	1.20 E-04	2.75	27500	0.03	305
Others	Curing and hardening agent	Proprietary	1.20 E-04	2.75	27500	0.03	305
Other organic materials	Gamma Butyrolactone	96-48-0	1.20 E-04	2.75	27500	0.03	305
Subtotal			4.35 E-03	100.0	1000000	1.11	11096

			Weight (g)			Percentage (%)	PPM
Package Totals			3.92 E-01			100	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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